

Features

- Low on-resistance
- ESD protected gate up to 2kV HBM
- High-speed switching
- Drive circuits can be simple
- Parallel use is easy

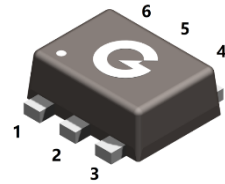
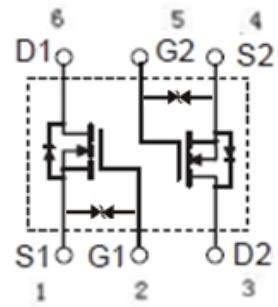
HF

Typical Applications

- N-channel enhancement mode effect transistor
- Switching application

Mechanical Data

- Case: SOT-563
- Molding Compound: UL Flammability Classification Rating 94V-0
- Terminals: Matte Tin-Plated Leads, Solderability-per MIL-STD-202, Method 208



SOT-563

Ordering Information

Part Number	Package	Shipping Quantity	Marking Code
2N7002HV	SOT-563	3000 pcs / Tape & Reel	7002K

Maximum Ratings (@ T_A = 25°C unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V _{DSS}	60	V
Gate -Source Voltage	V _{GSS}	±20	V
Continuous Drain Current	I _D	300	mA
Pulsed Drain Current (t _p ≤ 10μs) *4	I _{DM}	800	mA
Power Dissipation *1	P _D	0.25	W

Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance Junction-to-Air *1	R _{θJA}	500	°C/W
Thermal Resistance Junction-to-Case *1	R _{θJC}	342	°C/W
Thermal Resistance Junction-to-Lead *1	R _{θJL}	280	°C/W
Operating Junction Temperature Range	T _J	-55 ~ +150	°C
Storage Temperature Range	T _{STG}	-55 ~ +150	°C

Electrical Characteristics (@ T_A = 25°C unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
Static Characteristics						
V _{DSS}	Drain-Source Breakdown Voltage	V _{GS} = 0V, I _D = 250μA	60	-	-	V
I _{DSS}	Drain to Source Leakage Current	V _{DS} = 60V, V _{GS} = 0V	-	-	1	μA
I _{GSS}	Gate-body Leakage	V _{GS} = ±20V, V _{DS} = 0V	-	-	±10	μA
On Characteristics						
R _{DS(ON)}	Drain-Source On-resistance ^{*2}	V _{GS} = 5V, I _D = 0.05A	-	1.5	3	Ω
		V _{GS} = 10V, I _D = 0.5A	-	1.45	2.5	
V _{GS(TH)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = 250μA	1	1.5	2.5	V
Dynamic Characteristics						
C _{ISS}	Input Capacitance	V _{GS} = 0V V _{DS} = 20V f = 1.0MHz	-	47.2	-	pF
C _{OSS}	Output Capacitance		-	7.3	-	
C _{RSS}	Reverse Transfer Capacitance		-	4.7	-	
Switching Characteristics						
t _{d(on)}	Turn-on Delay Time ^{*3}	V _{DD} = 30V, I _D = 0.2A V _{GS} = 10V, R _G = 25Ω R _L = 150Ω	-	6	-	ns
t _r	Turn-on Rise Time ^{*3}		-	5	-	
t _{d(off)}	Turn-Off Delay Time ^{*3}		-	25	-	
t _f	Turn-Off Fall Time ^{*3}		-	15	-	
Q _G	Total Gate-Charge	V _{DS} = 10V	-	0.44	-	nC
Q _{GS}	Gate to Source Charge	V _{GS} = 4.5V	-	0.14	-	nC
Q _{GD}	Gate to Drain (Miller) Charge	I _D = 0.2A	-	0.2	-	nC
Source-Drain Diode Characteristics						
V _{SD}	Diode Forward Voltage ^{*2}	I _S = 0.3A, V _{GS} = 0V	-	0.85	1.2	V
I _S	Diode Continuous Forward Current	T _C = 25°C	-	-	0.3	A

Notes:

- 1、 Surface mounted on FR4 board, t ≤ 10 sec
- 2、 Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2%
- 3、 Guaranteed by design, not subject to production
- 4、 Pulse width limited by maximum junction temperature

Ratings and Characteristics Curves (@ $T_A = 25^\circ\text{C}$ unless otherwise specified)

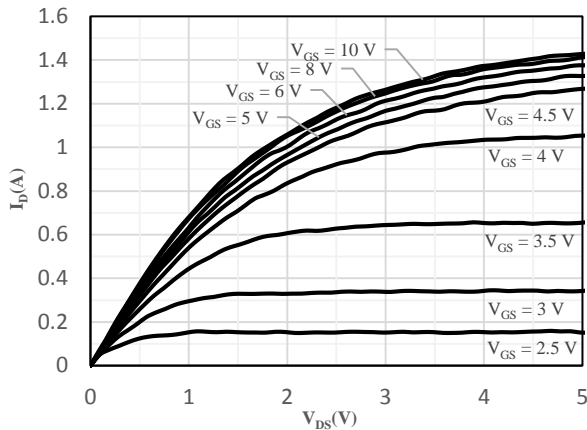


Fig 1 Typical Output Characteristics

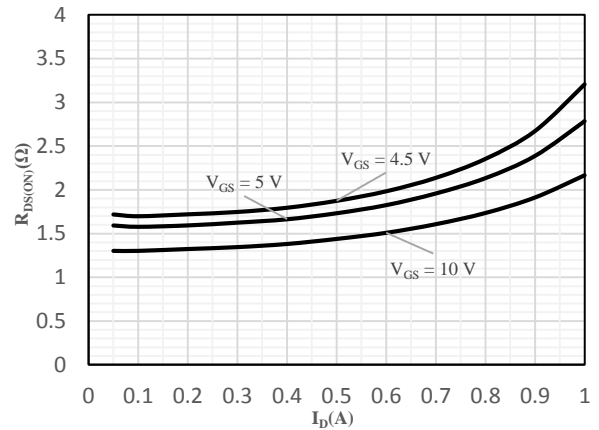


Fig 2 On-Resistance vs. Drain Current and Gate Voltage

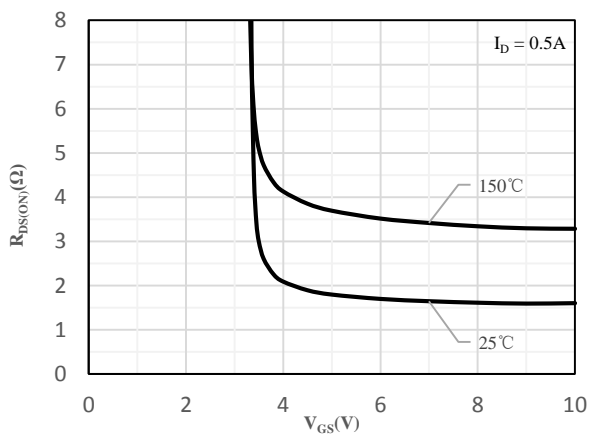


Fig 3 On-Resistance vs. Gate-Source Voltage

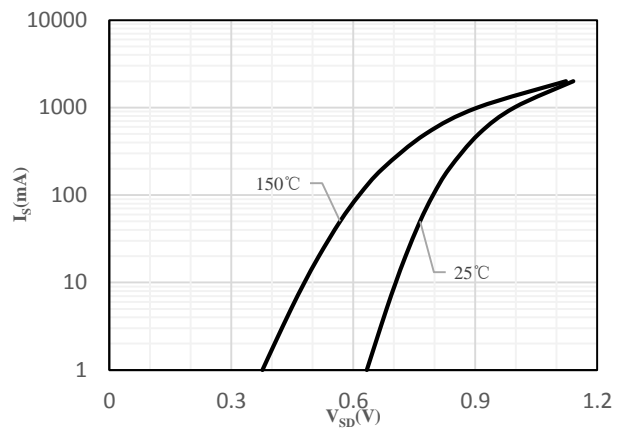


Fig 4 Body-Diode Characteristics

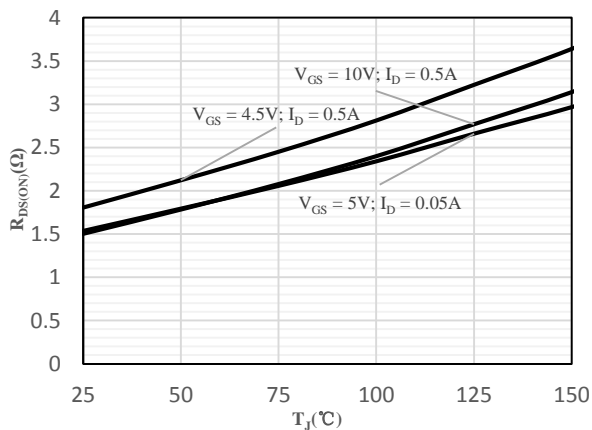


Fig 5 On-Resistance vs. Junction Temperature

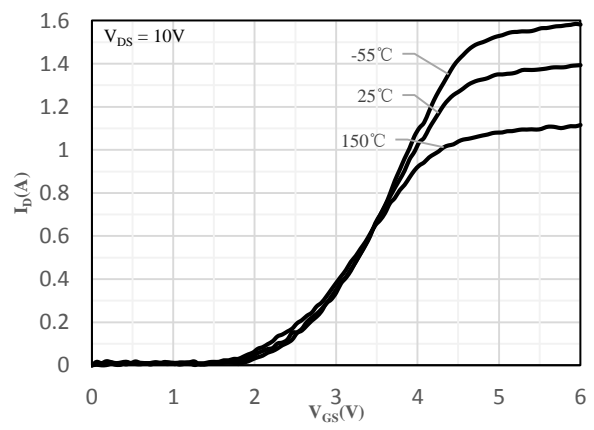


Fig 6 Transfer Characteristics

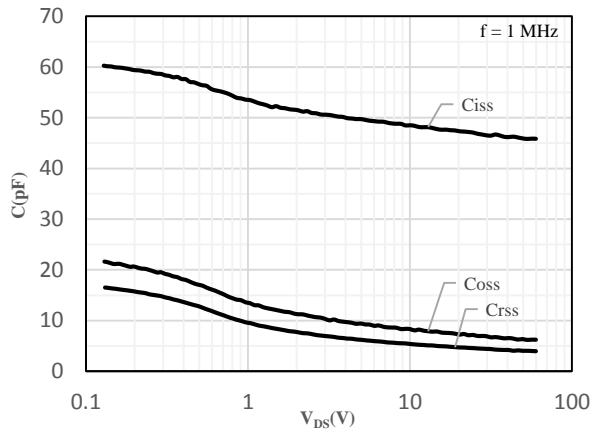


Fig 7 Capacitance Characteristics

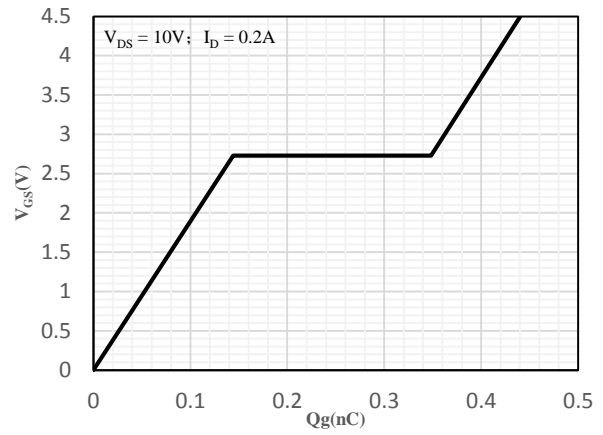


Fig 8 Gate-Charge Characteristics

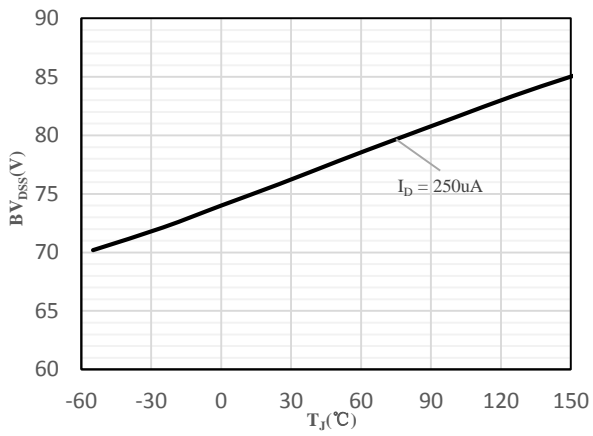


Fig 9 Breakdown Voltage vs. Junction
Temperature

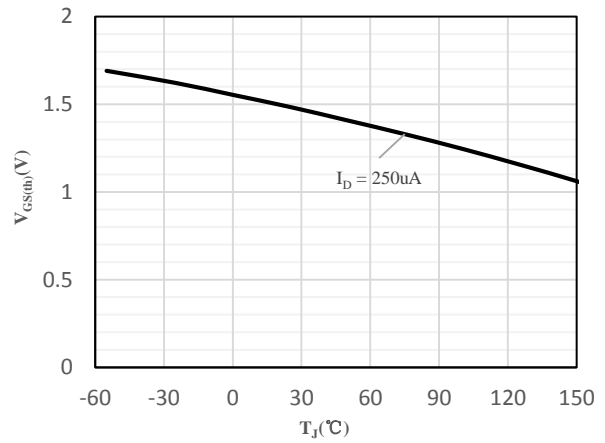
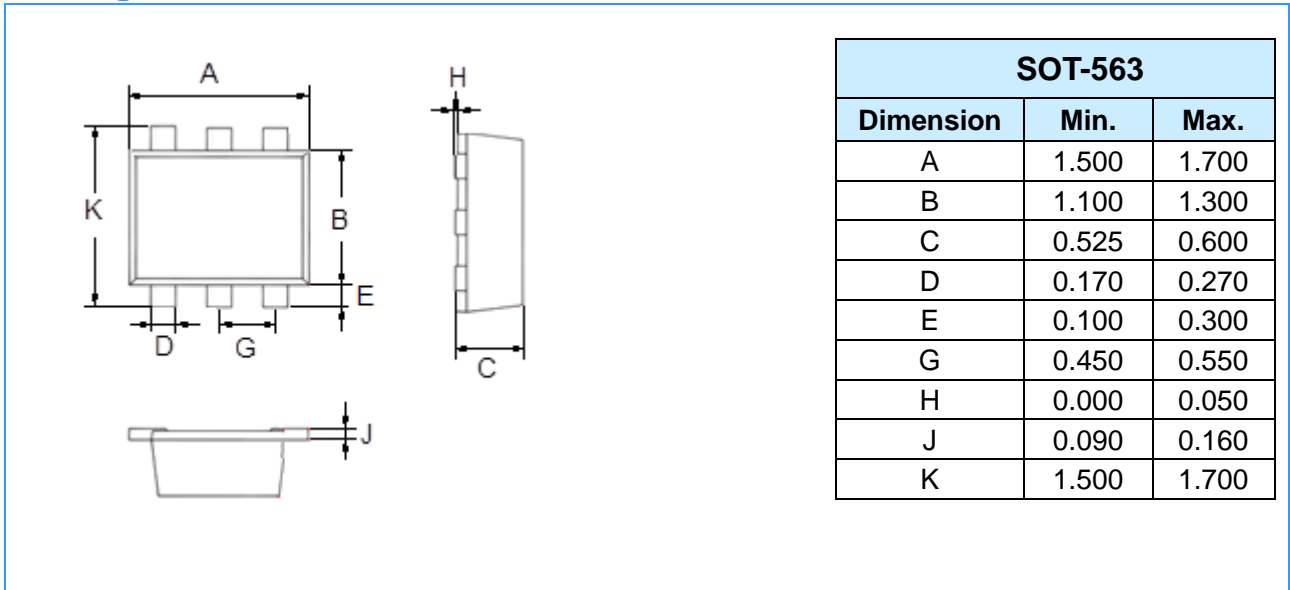
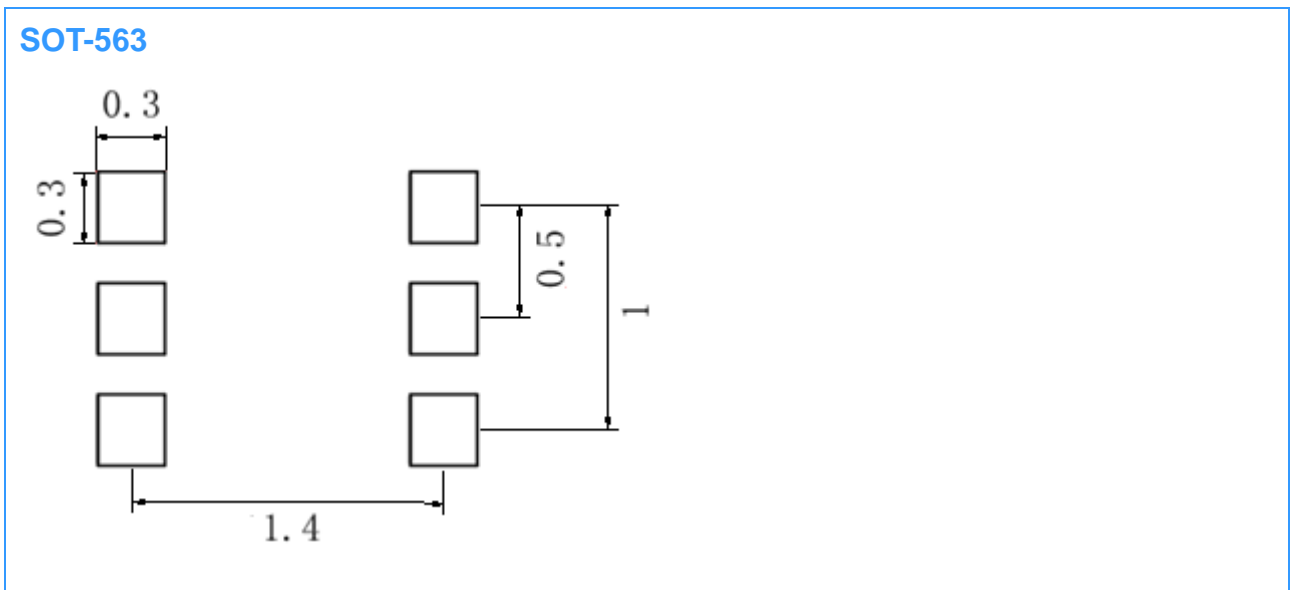


Fig 10 $V_{GS(th)}$ vs. Junction Temperature

Package Outline Dimensions (Unit: mm)



Mounting Pad Layout (Unit: mm)



IMPORTANT NOTICE

Changzhou Galaxy Century Microelectronics (GME) reserves the right to make changes without further notice to any product information (copyrighted) herein to make corrections, modifications, improvements, or other changes. GME does not assume any liability arising out of the application or use of any product described herein; neither does it convey any license under its patent rights, nor the rights of others.